ABSTRACT OF THE DISCLOSURE

A radiator structure has a circuit board, at least one conductive plate, a radiator board and at least two lock attachments, and reduces the entire radiator structure size to permit micro miniaturization designs and increase the space efficiency without affecting cooling efficiency. The radiator board has a deforming section, which undergoes resilience deformation facing the circuit board to absorb a contact pressure generated between the radiator board, the conductive plate and the microprocessor chip. Use of a spring to absorb the contact pressure is thus not required, which decreases the number of parts and manufacturing costs.